

FEATURES :

■ LOW INTERMODULATION DISTORTION

$IM_3 = -45\text{dBc}$ at $P_o = 35.0\text{dBm}$

■ HIGH POWER

$P_{1\text{dB}} = 45.5\text{dBm}$ at 5.9 to 6.4GHz

■ HIGH EFFICIENCY

$\eta_{\text{add}} = 39\%$ at 5.9 to 6.4GHz

■ HIGH GAIN

$G_{1\text{dB}} = 9.0\text{dB}$ at 5.9 to 6.4GHz

■ BROAD BAND INTERNALLY MATCHED

■ HERMETICALLY SEALED PACKAGE

RF PERFORMANCE SPECIFICATIONS ($T_a = 25^\circ\text{C}$)

CHARACTERISTICS	SYMBOL	CONDITION	UNIT	MIN.	TYP.	MAX.
Output Power at 1 dB Compression Point	$P_{1\text{dB}}$	$V_{\text{DS}} = 10\text{ V}$ $f = 5.9 \sim 6.4\text{ GHz}$	dBm	45.0	45.5	—
Power Gain at 1 dB Compression Point	$G_{1\text{dB}}$		dB	8.0	9.0	—
Drain Current	I_{DS}		A	—	8.0	9.0
Power Added Efficiency	η_{add}		%	—	39	—
3rd Order Intermodulation Distortion	IM_3	Note 1	dBc	-42	-45	—
Channel-Temperature Rise	ΔT_{ch}	$V_{\text{DS}} \times I_{\text{DS}} \times R_{\text{th}} (c-c)$	$^\circ\text{C}$	—	—	100

ELECTRICAL CHARACTERISTICS ($T_a = 25^\circ\text{C}$)

CHARACTERISTICS	SYMBOL	CONDITION	UNIT	MIN.	TYP.	MAX.
Transconductance	gm	$V_{\text{DS}} = 3\text{ V}$ $I_{\text{DS}} = 10.5\text{ A}$	mS	—	6500	—
Pinch-off Voltage	V_{GSoff}	$V_{\text{DS}} = 3\text{ V}$ $I_{\text{DS}} = 140\text{ mA}$	V	-1.0	-2.5	-4.0
Saturated Drain Current	I_{DSS}	$V_{\text{DS}} = 3\text{ V}$ $V_{\text{GS}} = 0\text{ V}$	A	—	20	26
Gate-Source Breakdown Voltage	V_{GSO}	$I_{\text{GS}} = -420\mu\text{A}$	V	-5	—	—
Thermal Resistance	$R_{\text{th}} (c-c)$	Channel to Case	$^\circ\text{C/W}$	—	1.0	1.3

Note 1 : 2 tone Test $P_{\text{out}} = 35\text{dBm}$ Single Carrier Level.

Recommended Gate Resistance(R_g) : $R_g = R_{g1}(10\ \Omega) + R_{g2}(18\ \Omega) = 28\ \Omega$ (MAX.)

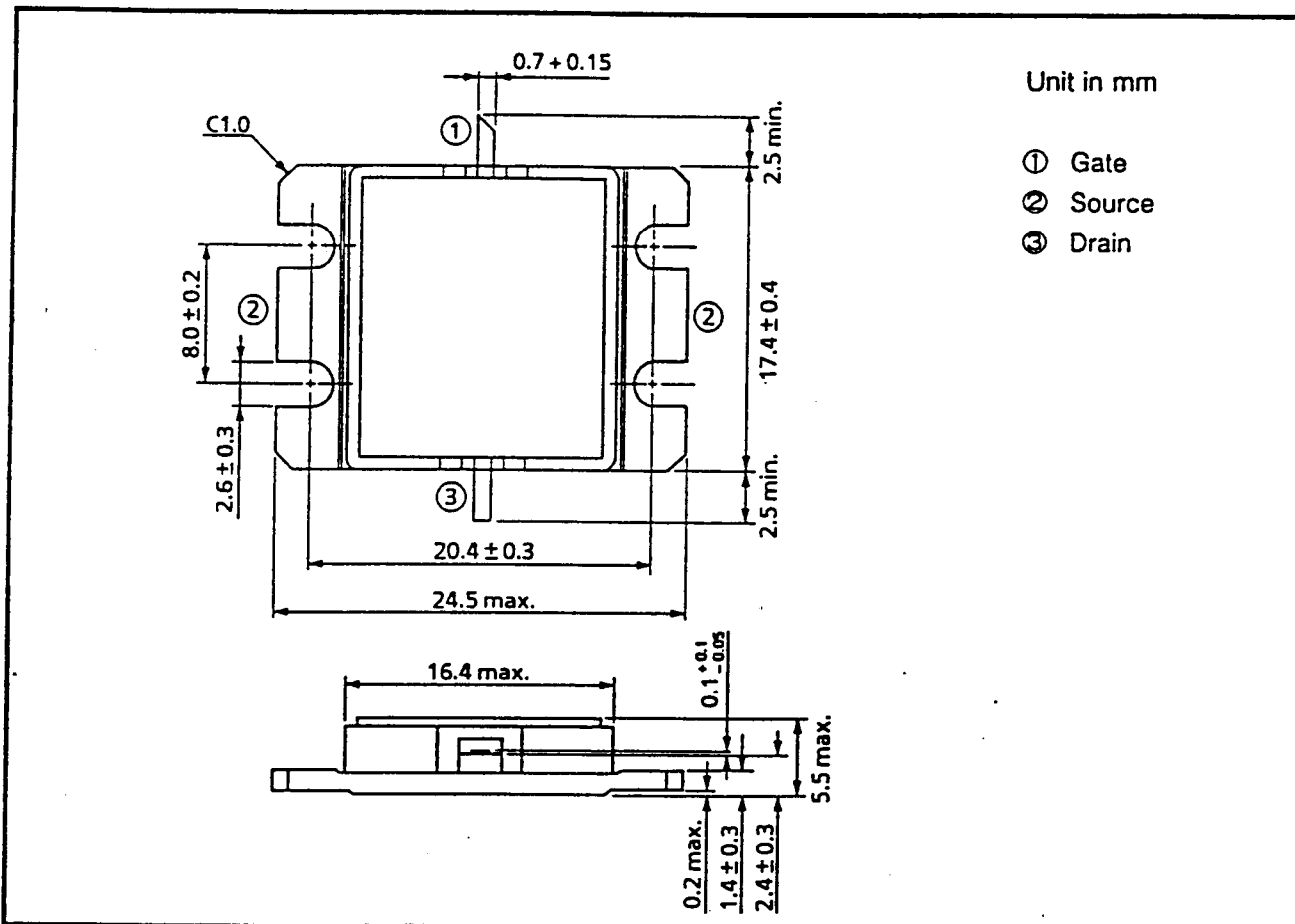
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ABSOLUTE MAXIMUM RATINGS ($T_a = 25^\circ\text{C}$)

CHARACTERISTICS	SYMBOL	UNIT	RATING
Drain-Source Voltage	V_{DS}	V	15
Gate-Source Voltage	V_{GS}	V	-5
Drain Current	I_{DS}	A	26
Total Power Dissipation ($T_C = 25^\circ\text{C}$)	P_T	W	115
Channel Temperature	T_{ch}	$^\circ\text{C}$	175
Storage Temperature	T_{stg}	$^\circ\text{C}$	-65~175

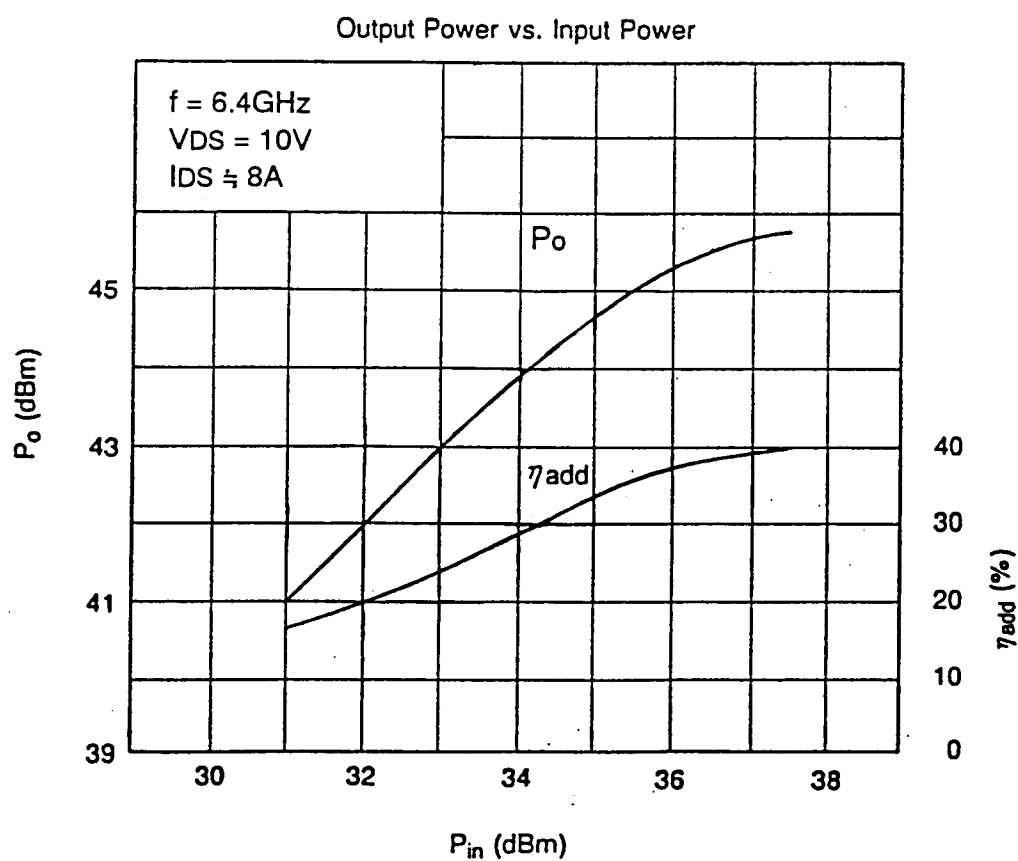
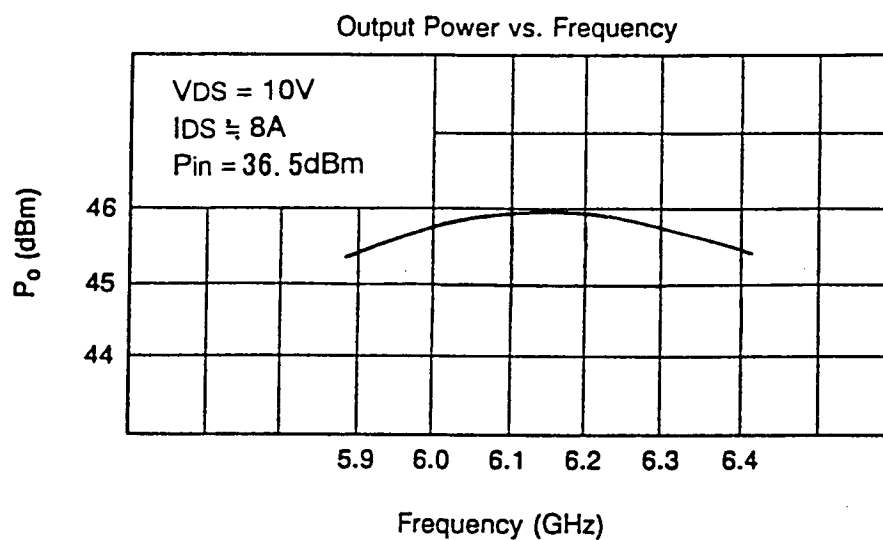
PACKAGE OUTLINE (2-16G1B)

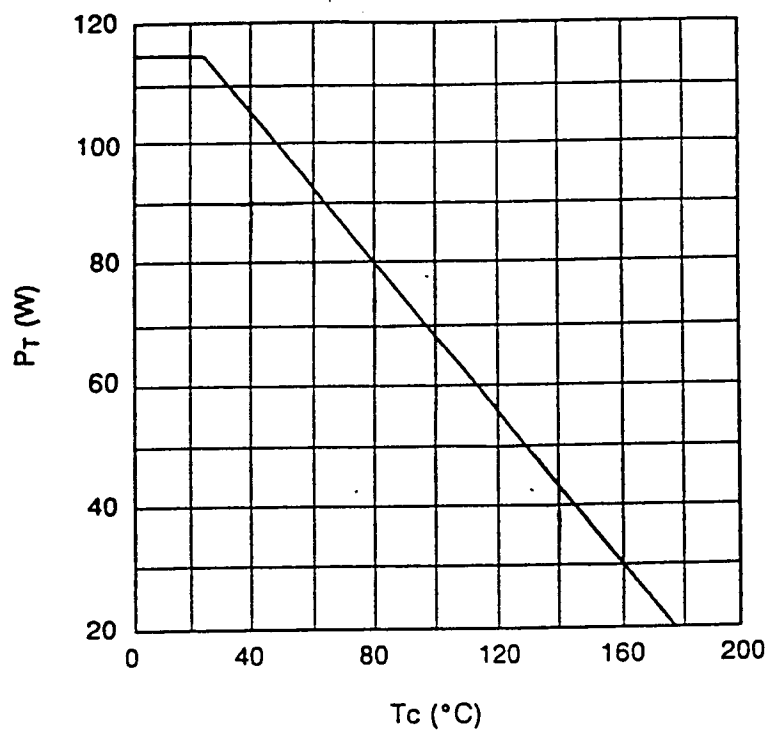
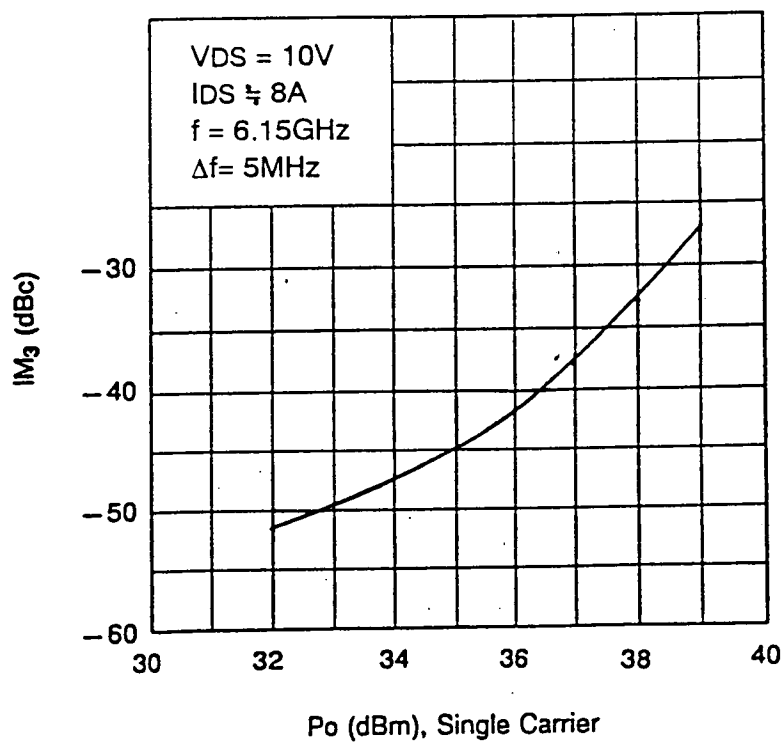


HANDLING PRECAUTIONS FOR PACKAGED TYPE

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C .

RF PERFORMANCES

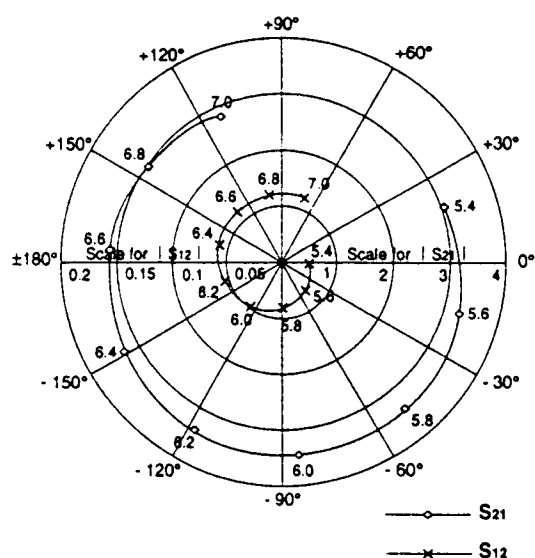
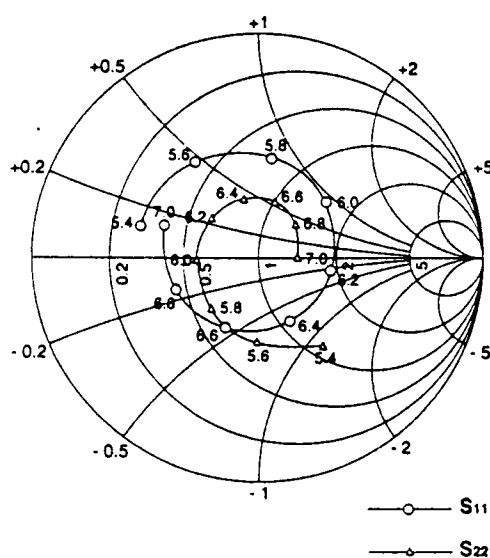


POWER DISSIPATION VS. CASE TEMPERATURE**IM₃ VS. OUTPUT POWER CHARACTERISTICS**

TIM5964-35SLA S-PARAMETERS (MAGN.and ANGLES)

$V_{DS} = 10V, I_{DS} = 8.0A$

$f = 5.4 \sim 7.0GHz$



FREQUENCY (GHz)	S_{11}		S_{21}		S_{12}		S_{22}	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
5.4	0.54	165	3.05	19	0.025	-2	0.48	-54
5.6	0.51	123	3.28	-16	0.033	-49	0.37	-91
5.8	0.45	83	3.41	-50	0.040	-89	0.30	-133
6.0	0.38	40	3.45	-85	0.048	-126	0.27	-179
6.2	0.32	-10	3.39	-118	0.054	-162	0.27	139
6.4	0.31	-64	3.28	-151	0.058	165	0.27	104
6.6	0.34	-115	3.13	176	0.060	132	0.26	74
6.8	0.39	-159	2.97	145	0.061	101	0.22	43
7.0	0.44	161	2.81	113	0.061	70	0.17	2